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#### DMB54D0UDW

#### N-CHANNEL ENHANCEMENT MODE MOSFET PLUS PNP TRANSISTOR

#### **Features**

- N-Channel MOSFET and PNP Transistor in One Package
- Low On-Resistance
- Very Low Gate Threshold Voltage, 1.0V max
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Ultra-Small Surface Mount Package
- Lead, Halogen and Antimony Free, RoHS Compliant (Note 2)
- ESD Protected MOSFET Gate up to 2kV
- "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

#### **Mechanical Data**

Case: SOT-363

Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0

Moisture Sensitivity: Level 1 per J-STD-020

Terminal Connections: See Diagram

Terminals: Finish - Matte Tin annealed over Alloy 42 lead frame. Solderable per MIL-STD-202, Method 208

Marking Information: See Page 5 Ordering Information: See Page 5

Weight: 0.006 grams (approximate)

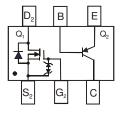
SOT-363







TOP VIEW



TOP VIEW

Internal Schematic

### Maximum Ratings – MOSFET, Q1 @TA = 25°C unless otherwise specified

Characte	ristic	Symbol	Value	Units		
Drain-Source Voltage		$V_{DSS}$	50	V		
Gate-Source Voltage		V <sub>GSS</sub>	±12	V		
Drain Current (Note 1)	Continuous	I <sub>D</sub>	160	mA		
Pulsed Drain Current (Note 1)		I <sub>DM</sub>	560	mA		

### Maximum Ratings - PNP Transistor, Q2 @TA = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	-50	V
Collector-Emitter Voltage	V <sub>CEO</sub>	-45	V
Emitter-Base Voltage	V <sub>EBO</sub>	-5.0	V
Collector Current	I <sub>C</sub>	-100	mA

### Thermal Characteristics, Total Device @TA = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 1)	P <sub>D</sub>	250	mW
Thermal Resistance, Junction to Ambient (Note 1)	$R_{ heta JA}$	500	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

Notes:

- 1. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.
- No purposefully added lead. Halogen and Antimony Free.
- 3. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead\_free/index.php.



# Electrical Characteristics - MOSFET @TA = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition		
OFF CHARACTERISTICS (Note 2)								
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	50	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>		_	10	μΑ	$V_{DS} = 50V, V_{GS} = 0V$		
Gate-Body Leakage	I <sub>GSS</sub>	_	_	1.0 5.0	μА	$V_{GS} = \pm 8V, V_{DS} = 0V$ $V_{GS} = \pm 12V, V_{DS} = 0V$		
ON CHARACTERISTICS (Note 2)	•					•		
Gate Threshold Voltage	V <sub>GS(th)</sub>	0.7	0.8	1.0	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$		
Static Drain-Source On-Resistance		_	3.1	4	Ω	$V_{GS} = 4V, I_{D} = 100mA$		
Static Drain-Source On-Resistance	R <sub>DS</sub> (ON)	_	4	5		$V_{GS} = 2.5V, I_D = 80mA$		
Forward Transconductance	g <sub>FS</sub>	180	_	_	mS	$V_{DS} = 10V, I_D = 100mA,$ f = 1.0KHz		
DYNAMIC CHARACTERISTICS	DYNAMIC CHARACTERISTICS							
Input Capacitance	Ciss		25	_	рF	101/1/		
Output Capacitance	Coss	_	5	_	рF	$V_{DS} = 10V, V_{GS} = 0V,$ - f = 1.0MHz		
Reverse Transfer Capacitance	Crss	_	2.1	_	pF	TI = 1.0IVII IZ		

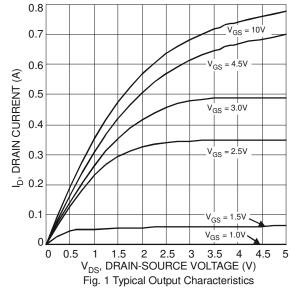
## Electrical Characteristics - PNP Transistor @TA = 25°C unless otherwise specified

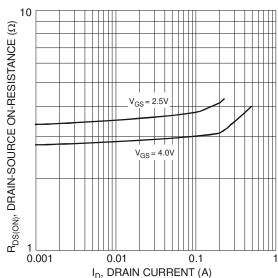
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage (Note 4)	V <sub>(BR)CBO</sub>	-50	_		V	$I_C = 10\mu A, I_B = 0$
Collector-Emitter Breakdown Voltage (Note 4)	V <sub>(BR)CEO</sub>	-45		—	V	$I_C = 10 \text{mA}, I_B = 0$
Emitter-Base Breakdown Voltage (Note 4)	$V_{(BR)EBO}$	-5			V	$I_E = 1 \mu A, I_C = 0$
DC Current Gain (Note 4)	h <sub>FE</sub>	220	290	475	l	$V_{CE} = -5.0V$ , $I_{C} = -2.0mA$
Collector-Emitter Saturation Voltage (Note 4)	V <sub>CE(SAT)</sub>	_		-100 -400	mV	$I_C = -10\text{mA}, I_B = -0.5\text{mA}$
	` ′					I <sub>C</sub> = -100mA, I <sub>B</sub> = -5.0mA
Base-Emitter Saturation Voltage (Note 4)	V <sub>BE(SAT)</sub>		-700 -900	_	mV	$I_C = -10 \text{mA}, I_B = -0.5 \text{mA}$ $I_C = -100 \text{mA}, I_B = -5.0 \text{mA}$
Base-Emitter Voltage (Note 4)	V <sub>BE(ON)</sub>	-600 —		-750 -820	mV	$V_{CE} = -5.0V$ , $I_{C} = -2.0mA$ $V_{CE} = -5.0V$ , $I_{C} = -10mA$
Collector-Cutoff Current (Note 4)	I <sub>CBO</sub>			-15 -4.0	nA μA	V <sub>CB</sub> = -30V V <sub>CB</sub> = -30V, T <sub>A</sub> = 150°C
Collector-Emitter Cut-Off Current (Note 4)	I <sub>CES</sub>			-100	nA	V <sub>CE</sub> = -45V
Gain Bandwidth Product	f <sub>T</sub>	100		_	MHz	$V_{CE} = -5.0V$ , $I_{C} = -10mA$ , $f = 100MHz$
Output Capacitance	C <sub>OB</sub>			4.5	pF	$V_{CB} = -10V, f = 1.0MHz$
Noise Figure	NF			10	dB	$I_{C}$ = -0.2mA, $V_{CE}$ = -5.0Vdc, $R_{S}$ = 2.0K $\Omega$ , f = 1.0KHz, BW = 200Hz

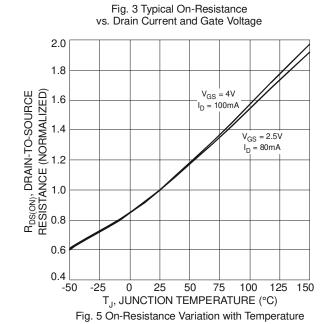
Notes: 4. Short duration pulse test used to minimize self-heating effect.

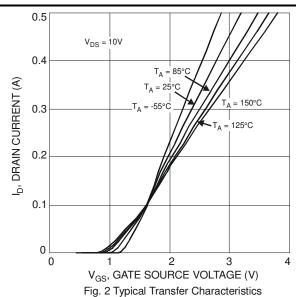


### **MOSFET**









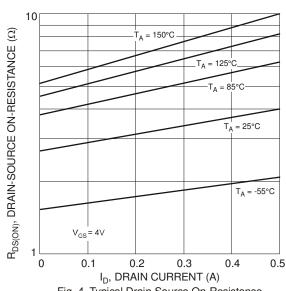
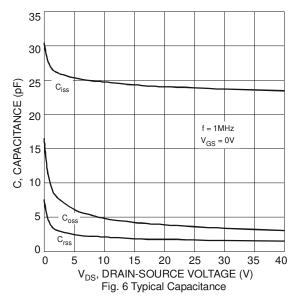


Fig. 4 Typical Drain-Source On-Resistance vs. Drain Current and Temperature





## **MOSFET** (continued)

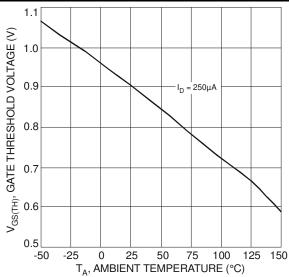


Fig. 7 Gate Threshold Variation vs. Ambient Temperature

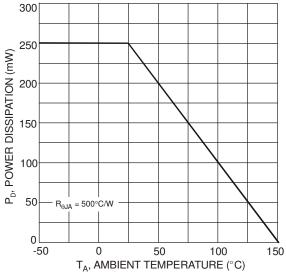
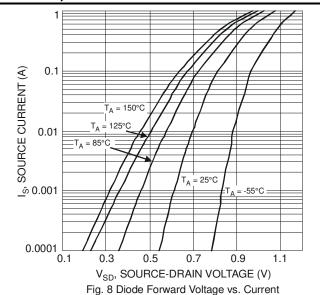


Fig. 9 Derating Curve - Total Package Power Dissipation





### **PNP Transistor**

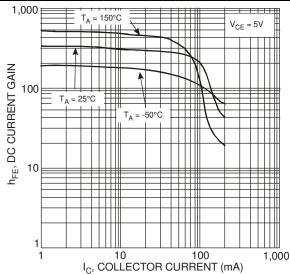


Fig. 10 Typical DC Current Gain vs. Collector Current

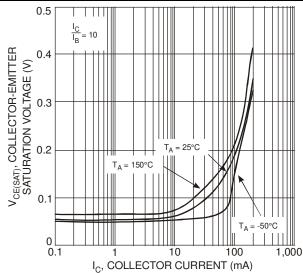


Fig. 11 Collector-Emitter Saturation Voltage vs. Collector Current

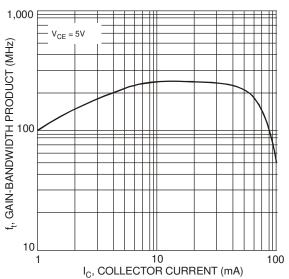


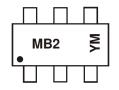
Fig. 12 Typical Gain-Bandwidth Product vs. Collector Current

### Ordering Information (Note 5)

Part Number	Case	Packaging
DMB54D0UDW-7	SOT-363	3000/Tape & Reel

Notes: 5. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

# **Marking Information**



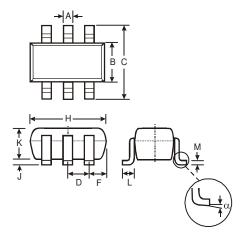
MB2 = Marking Code YM = Date Code Marking Y = Year (ex: V = 2008) M = Month (ex: 9 = September)

Date Code Key

Year	2008		2009	2010		2011	2012		2013	2014		2015
Code	V		W	X		Υ	Z		Α	В		С
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D

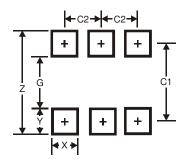


## **Package Outline Dimensions**



	SOT-363					
Dim	Min	Max				
Α	0.10	0.30				
В	1.15	1.35				
C	2.00	2.20				
D	0.65	Тур				
F	0.40	0.45				
Н	1.80	2.20				
J	0 0.10					
K	0.90	1.00				
L	0.25	0.40				
M	0.10	0.22				
α	0°	8°				
All Di	mensions	in mm				

# **Suggested Pad Layout**



Dimensions	Value (in mm)
Z	2.5
G	1.3
X	0.42
Υ	0.6
C1	1.9
C2	0.65



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  - 2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.
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